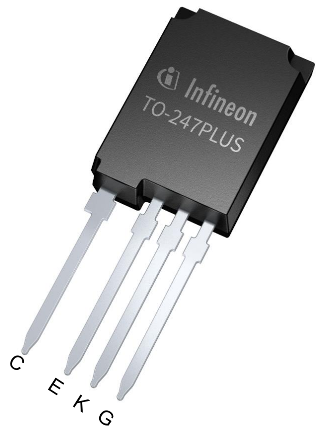
Final datasheet

High speed and low saturation voltage 750 V TRENCHSTOP™ IGBT7 technology co-packed with soft and fast recovery Emitter Controlled 7 diode



Features

- V_{CE} = 750 V
- I_C = 150 A
- Low switching losses
- Very low collector-emitter saturation voltage V_{CEsat}
- Very soft, fast recovery antiparallel diode
- Smooth switching behavior
- Humidity robustness
- Optimized for hard switching, two- and three-level topologies
- Complete product spectrum and PSpice Models: http://www.infineon.com/igbt/

Potential applications

- Industrial UPS
- EV Charging
- String inverter
- Energy storage systems (ESS)

Product validation

- Qualified for industrial applications according to the relevant tests of JEDEC47/20/22

Lead-free

Green

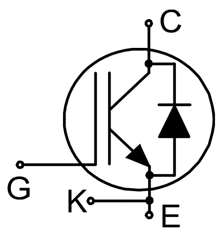
Halogen-free

RoHS

Description

Pin definition:

- Pin C & backside – Collector
- Pin E – Emitter
- Pin K – Kelvin emitter
- Pin G – Gate



Type	Package	Marking
IKY150N75EH7	PG-TO247-4-U10	K150GEH7

Table of contents

1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Internal emitter inductance measured 5 mm (0.197 in.) from case	L_E			13		nH
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Thermal resistance, junction-ambient	$R_{th(j-a)}$				40	K/W
IGBT thermal resistance, junction-case	$R_{th(j-c)}$			0.19	0.24	K/W
Diode thermal resistance, junction-case	$R_{th(j-c)}$			0.26	0.33	K/W

2 IGBT

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CE}	$T_{vj} \geq 25$ °C		750	V
DC collector current, limited by T_{vjmax}	I_C	limited by bondwire	$T_c = 25$ °C	160	A
			$T_c = 100$ °C	160	
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpulse}			600	A
Turn-off safe operating area		$V_{CE} \leq 750$ V, $t_p \leq 1$ µs, $T_{vj} \leq 175$ °C		600	A
Gate-emitter voltage	V_{GE}			±20	V
Transient gate-emitter voltage	V_{GE}	$t_p \leq 10$ µs, $D < 0.01$		±30	V
Power dissipation	P_{tot}		$T_c = 25$ °C	625	W
			$T_c = 100$ °C	313	

Table 3 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	V_{CEsat}	$I_C = 150$ A, $V_{GE} = 15$ V	$T_{vj} = 25$ °C		1.45	1.75	V
			$T_{vj} = 175$ °C		1.75		

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Gate-emitter threshold voltage	V_{GEth}	I_C = 1.32 mA, V_{CE} = V_{GE}		3.2	4	4.8	V
Zero gate-voltage collector current	I_{CES}	V_{CE} = 750 V, V_{GE} = 0 V	T_{vj} = 25 °C			50	µA
			T_{vj} = 175 °C		4500		
Gate-emitter leakage current	I_{GES}	V_{CE} = 0 V, V_{GE} = 20 V				100	nA
Transconductance	g_{fs}	I_C = 150 A, V_{CE} = 20 V			186		S
Input capacitance	C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V, f = 100 kHz			7950		pF
Output capacitance	C_{oes}	V_{CE} = 25 V, V_{GE} = 0 V, f = 100 kHz			222		pF
Reverse transfer capacitance	C_{res}	V_{CE} = 25 V, V_{GE} = 0 V, f = 100 kHz			30		pF
Gate charge	Q_G	V_{CC} = 600 V, I_C = 150 A, V_{GE} = 15 V			300		nC
Turn-on delay time	$t_{d(on)}$	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		43		ns
			T_{vj} = 175 °C, I_C = 150 A		41		
Rise time (inductive load)	t_r	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		23		ns
			T_{vj} = 175 °C, I_C = 150 A		28		
Turn-off delay time	$t_{d(off)}$	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		324		ns
			T_{vj} = 175 °C, I_C = 150 A		363		
Fall time (inductive load)	t_f	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		23		ns
			T_{vj} = 175 °C, I_C = 150 A		59		
Turn-on energy	E_{on}	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		3		mJ
			T_{vj} = 175 °C, I_C = 150 A		4		
Turn-off energy	E_{off}	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		2.5		mJ
			T_{vj} = 175 °C, I_C = 150 A		4		

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Total switching energy	E_{ts}	V_{CC} = 400 V, V_{GE} = 0/15 V, $R_{G(on)}$ = 10 Ω, $R_{G(off)}$ = 10 Ω	T_{vj} = 25 °C, I_C = 150 A		5.4		mJ
			T_{vj} = 175 °C, I_C = 150 A		8		
Operating junction temperature	T_{vj}			-40		175	°C

3 Diode

Table 4 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Diode forward current, limited by T_{vjmax}	I_F	limited by bondwire	T_c = 25 °C	160	A
			T_c = 100 °C	149	
Diode pulsed current, t_p limited by T_{vjmax}	I_{Fpulse}			600	A
Power dissipation	P_{tot}		T_c = 25 °C	455	W
			T_c = 100 °C	227	

Table 5 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode forward voltage	V_F	I_F = 150 A	T_{vj} = 25 °C		1.65	2	V
			T_{vj} = 175 °C		1.6		
Diode reverse recovery time	t_{rr}	V_R = 400 V, $R_{G(on)}$ = 10 Ω	T_{vj} = 25 °C, I_F = 150 A		102		ns
			T_{vj} = 175 °C, I_F = 150 A		181		
Diode reverse recovery charge	Q_{rr}	V_R = 400 V, $R_{G(on)}$ = 10 Ω	T_{vj} = 25 °C, I_F = 150 A		4.1		µC
			T_{vj} = 175 °C, I_F = 150 A		11.9		
Diode peak reverse recovery current	I_{rrm}	V_R = 400 V, $R_{G(on)}$ = 10 Ω	T_{vj} = 25 °C, I_F = 150 A		82.8		A
			T_{vj} = 175 °C, I_F = 150 A		132.5		

(table continues...)

Table 5 **(continued) Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode peak rate of fall of reverse recovery current	di_{rr}/dt	V_R = 400 V, $R_{G(on)}$ = 10 Ω	T_{vj} = 25 °C, I_F = 150 A		-1010		A/µs
			T_{vj} = 175 °C, I_F = 150 A		-897		
Reverse recovery energy	E_{rec}	V_R = 400 V, $R_{G(on)}$ = 10 Ω	T_{vj} = 25 °C, I_F = 150 A		0.98		mJ
			T_{vj} = 175 °C, I_F = 150 A		3.35		
Operating junction temperature	T_{vj}			-40		175	°C

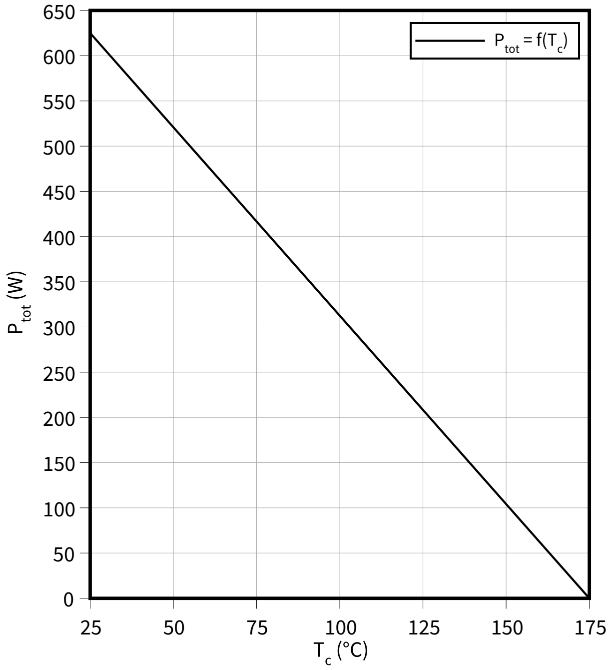
***Note**: For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.*

Electrical Characteristic, at T_{vj} = 25°C, unless otherwise specified.

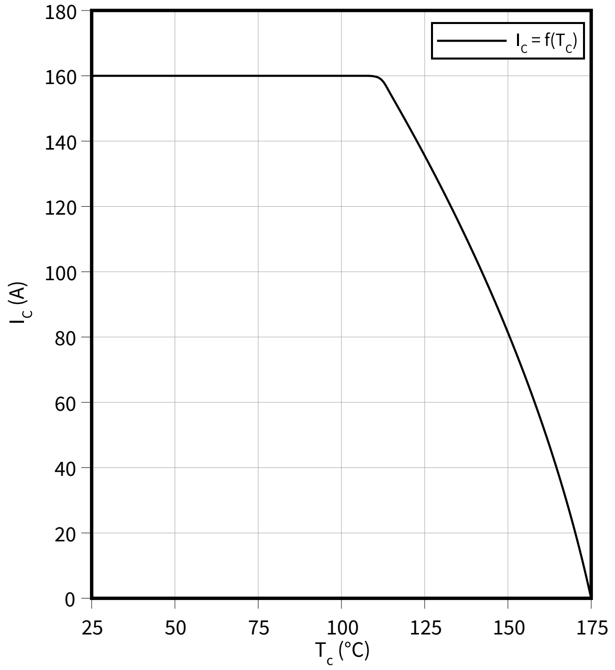
Dynamic test circuit, parasitic inductance L_σ = 15 nH, parasitic capacitor C_σ = 16 pF from Fig. E. Energy losses include “tail” and diode reverse recovery.

4 Characteristics diagrams

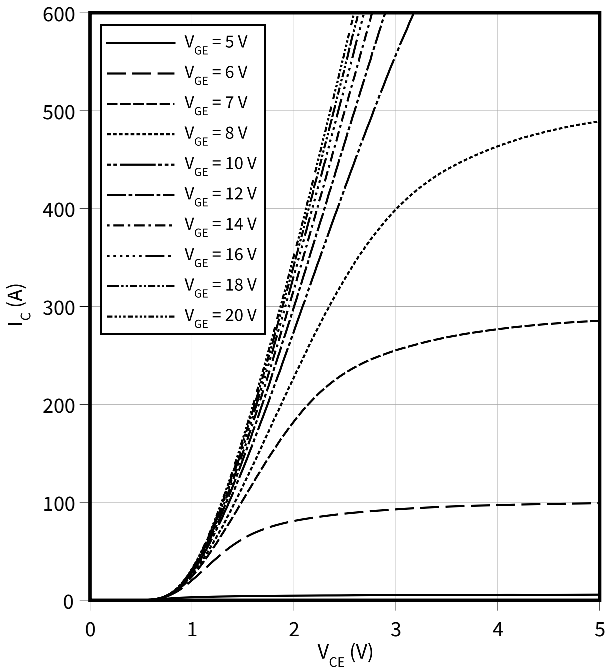
Power dissipation as a function of case temperature
$P_{tot} = f(T_c)$
$T_{vj} \leq 175$ °C



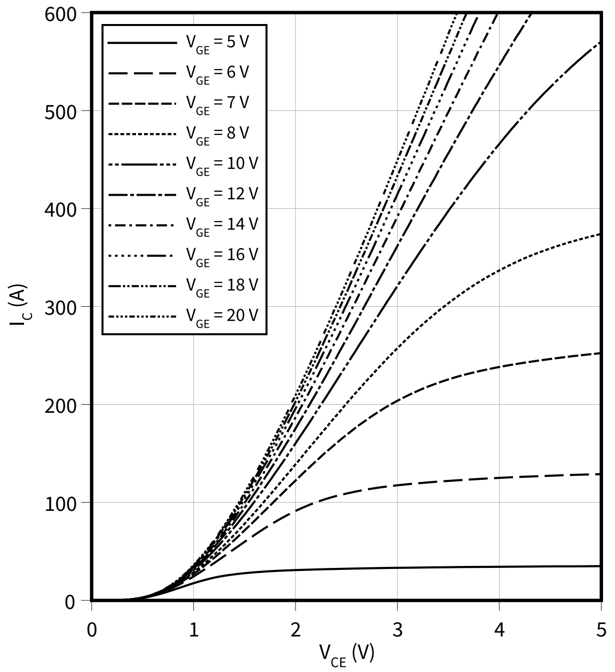
Collector current as a function of case temperature
$I_C = f(T_c)$
$T_{vj} \leq 175$ °C, $V_{GE} = 15$ V



Typical output characteristic
$I_C = f(V_{CE})$
$T_{vj} = 25$ °C



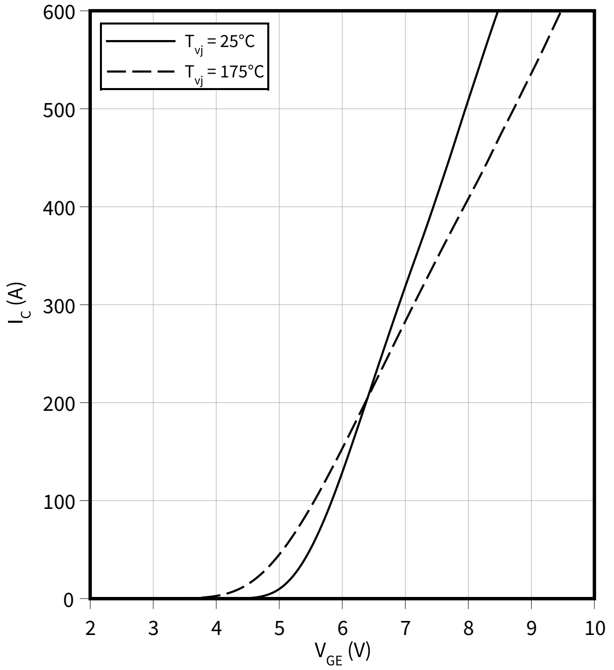
Typical output characteristic
$I_C = f(V_{CE})$
$T_{vj} = 175$ °C



Typical transfer characteristic

$I_C = f(V_{GE})$

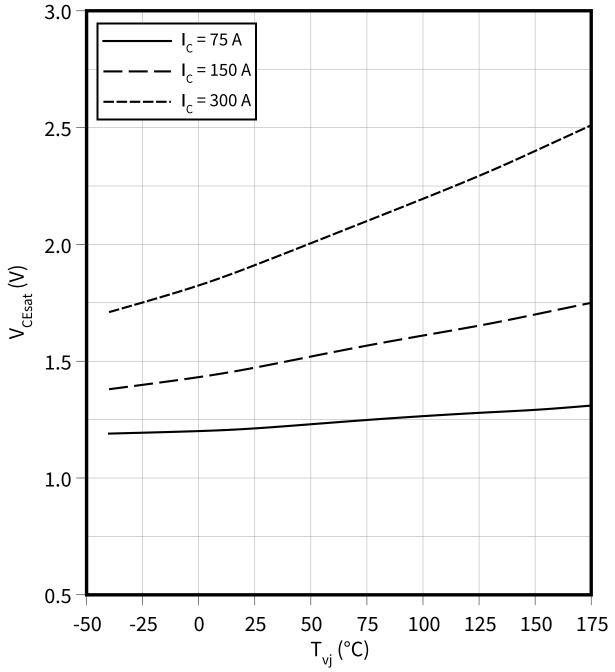
$V_{CE} = 20$ V



Typical collector-emitter saturation voltage as a function of junction temperature

$V_{CEsat} = f(T_{vj})$

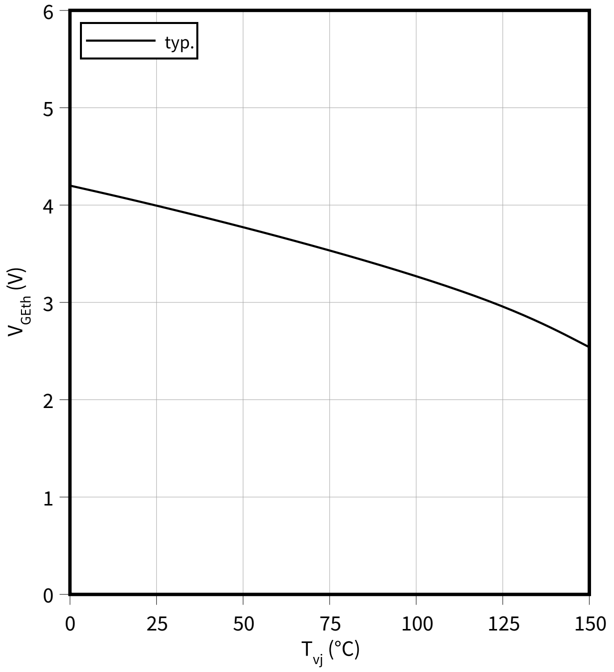
$V_{GE} = 15$ V



Gate-emitter threshold voltage as a function of junction temperature

$V_{GEth} = f(T_{vj})$

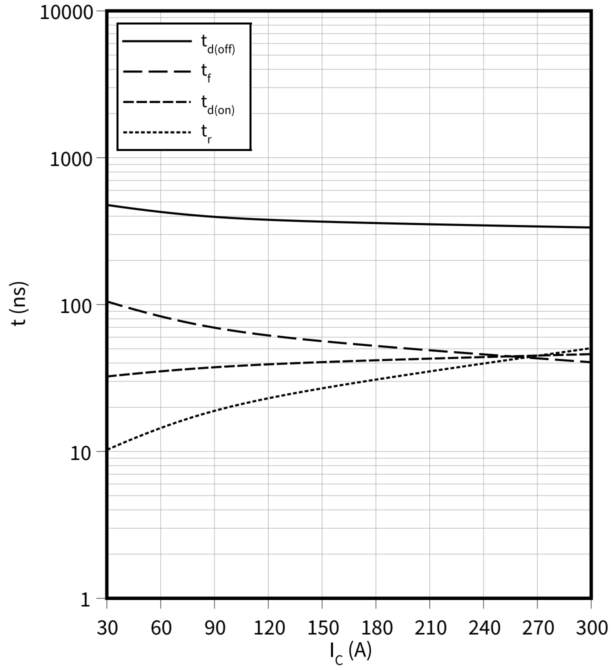
$I_C = 1.32$ mA



Typical switching times as a function of collector current

$t = f(I_C)$

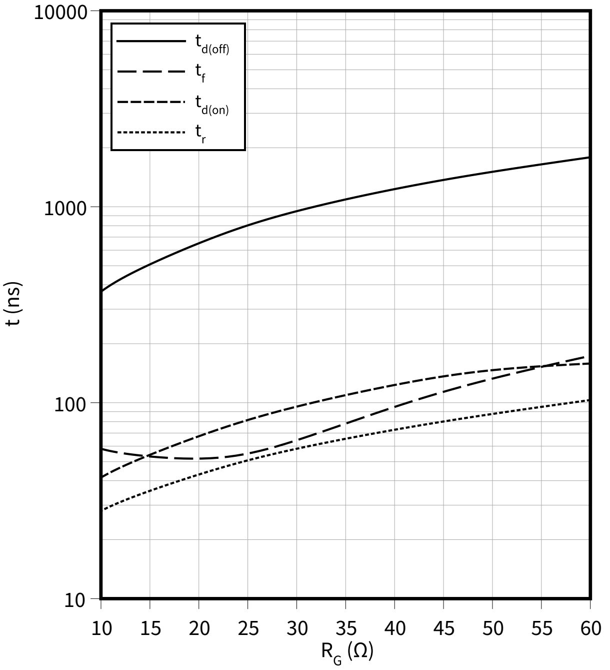
$V_{CC} = 400$ V, $T_{vj} = 175$ °C, $V_{GE} = 0/15$ V, $R_G = 10\ \Omega$



Typical switching times as a function of gate resistor

$t = f(R_G)$

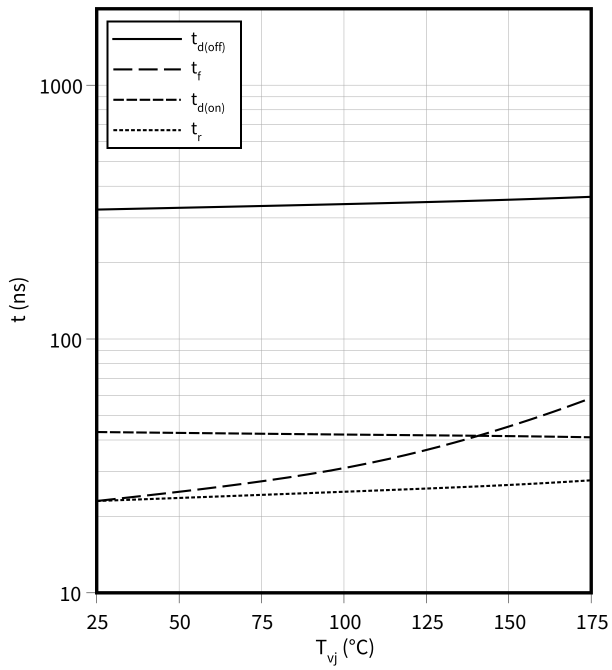
$I_C = 150$ A, $V_{CC} = 400$ V, $T_{vj} = 175$ °C, $V_{GE} = 0/15$ V



Typical switching times as a function of junction temperature

$t = f(T_{vj})$

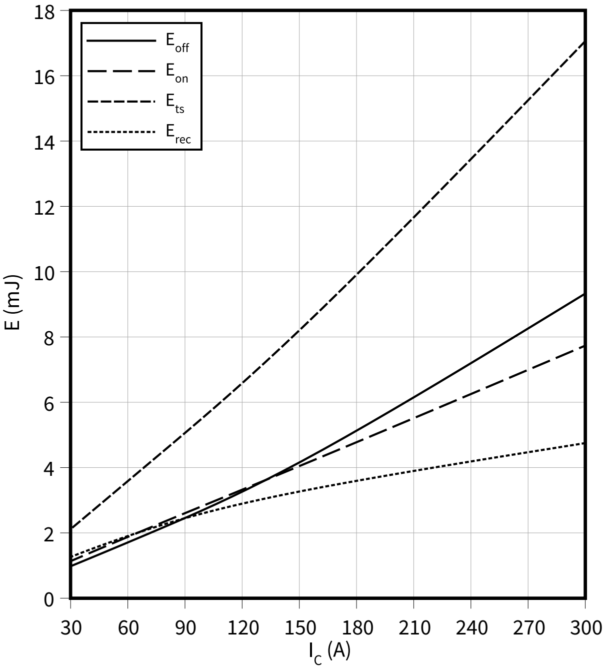
$I_C = 150$ A, $V_{CC} = 400$ V, $V_{GE} = 0/15$ V, $R_G = 10$ Ω



Typical switching energy losses as a function of collector current

$E = f(I_C)$

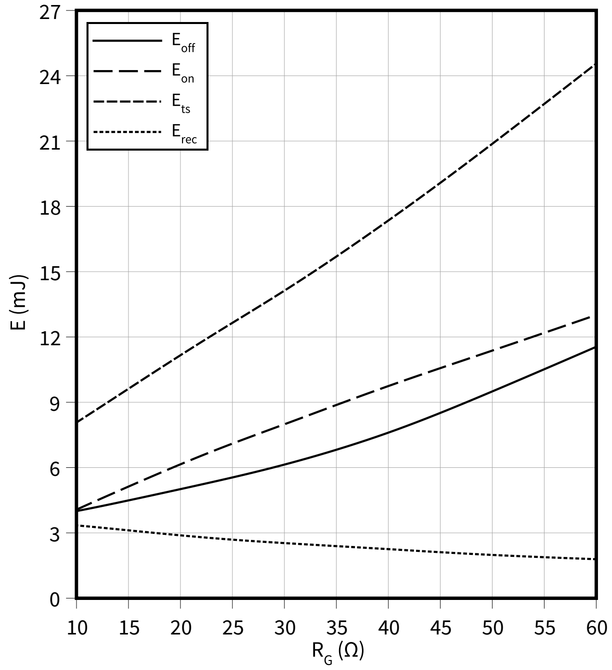
$V_{CC} = 400$ V, $T_{vj} = 175$ °C, $V_{GE} = 0/15$ V, $R_G = 10$ Ω



Typical switching energy losses as a function of gate resistor

$E = f(R_G)$

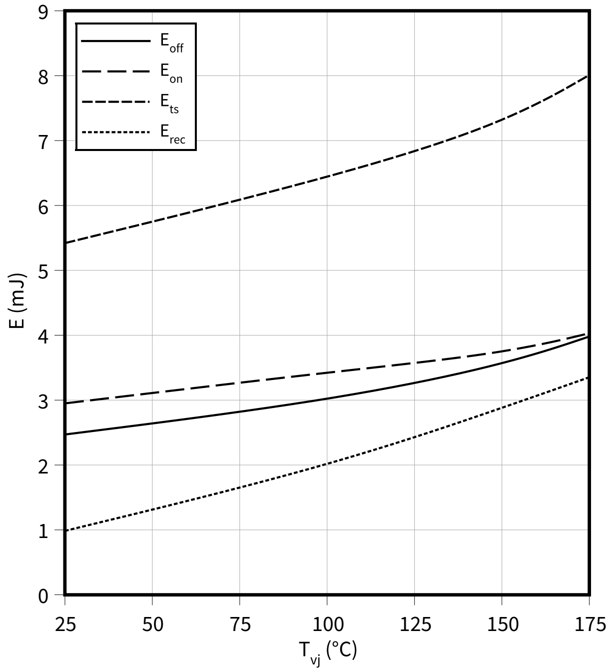
$I_C = 150$ A, $V_{CC} = 400$ V, $T_{vj} = 175$ °C, $V_{GE} = 0/15$ V



Typical switching energy losses as a function of junction temperature

$E = f(T_{vj})$

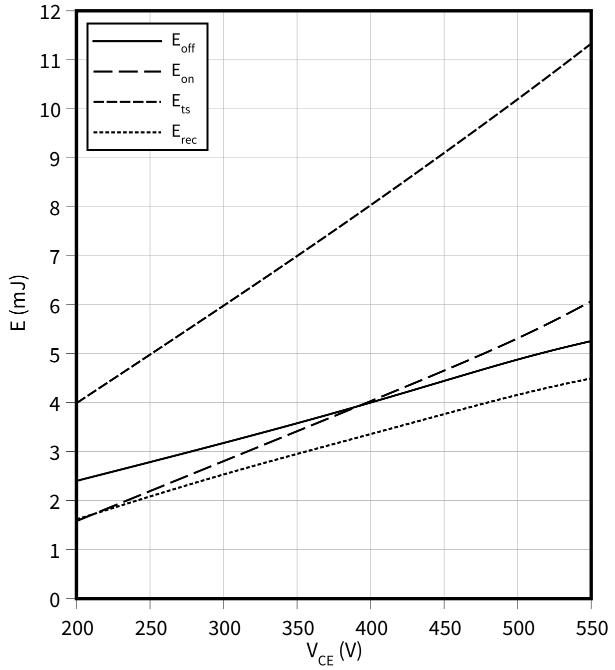
$I_C = 150$ A, $V_{CC} = 400$ V, $V_{GE} = 0/15$ V, $R_G = 10\ \Omega$



Typical switching energy losses as a function of collector emitter voltage

$E = f(V_{CE})$

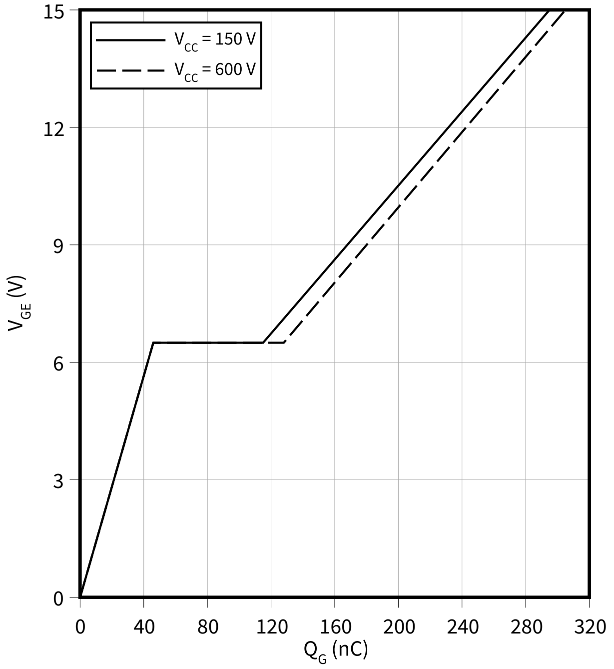
$I_C = 150$ A, $T_{vj} = 175$ °C, $V_{GE} = 0/15$ V, $R_G = 10\ \Omega$



Typical gate charge

$V_{GE} = f(Q_G)$

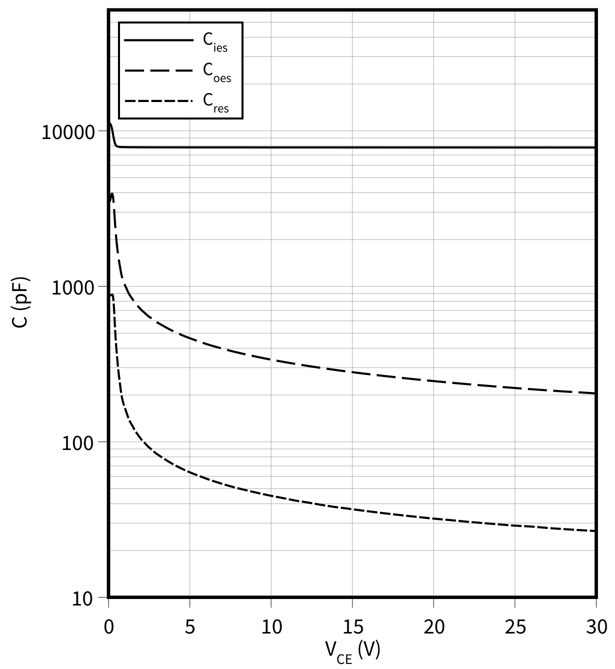
$I_C = 150$ A



Typical capacitance as a function of collector-emitter voltage

$C = f(V_{CE})$

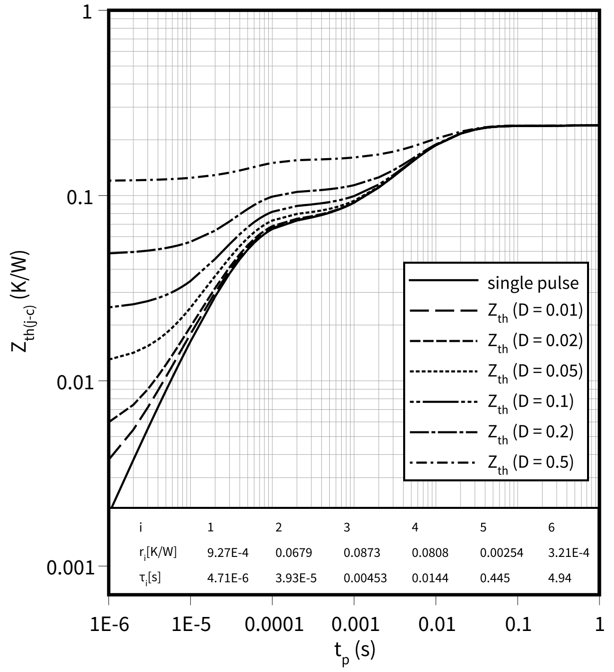
$f = 100$ kHz, $V_{GE} = 0$ V



IGBT transient thermal impedance as a function of pulse width

$Z_{th(j-c)} = f(t_p)$

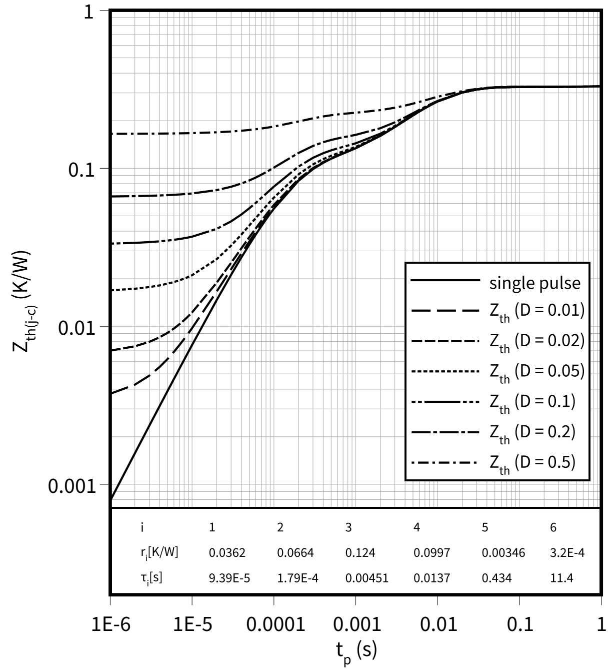
$D = t_p/T$



Diode transient thermal impedance as a function of pulse width

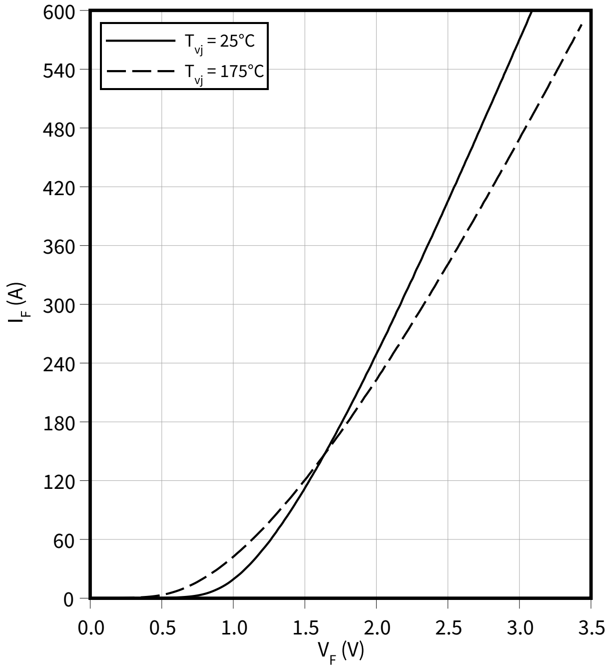
$Z_{th(j-c)} = f(t_p)$

$D = t_p/T$



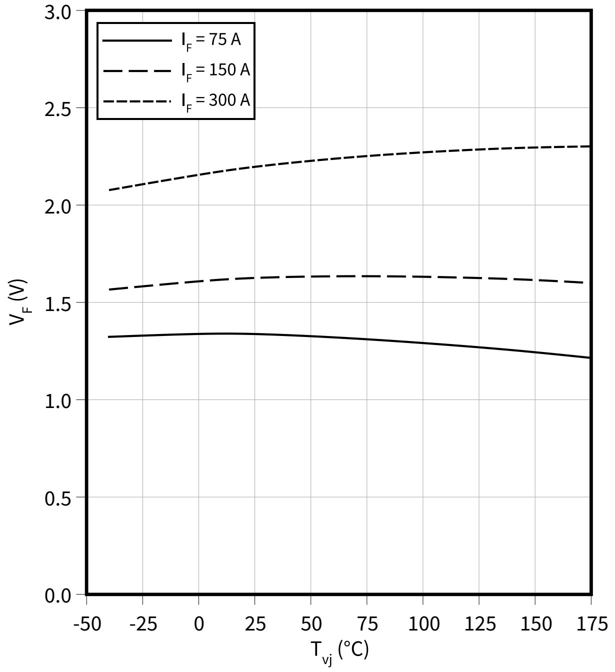
Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



Typical diode forward voltage as a function of junction temperature

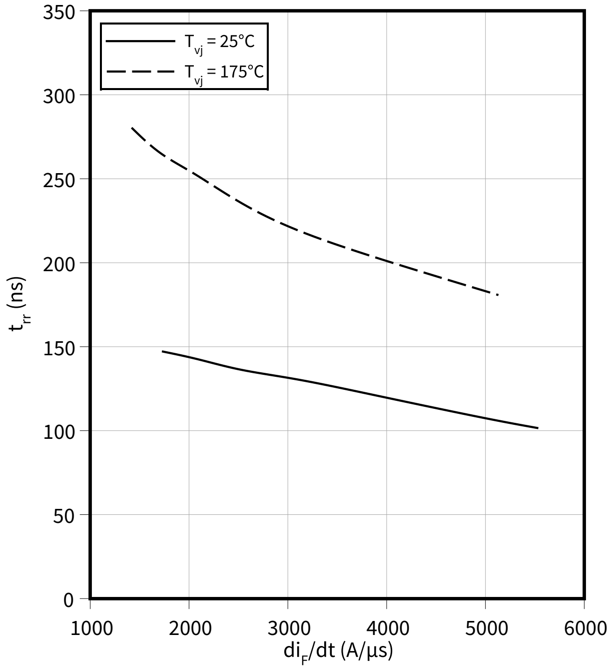
$V_F = f(T_{vj})$



Typical reverse recovery time as a function of diode current slope

$t_{rr} = f(di_F/dt)$

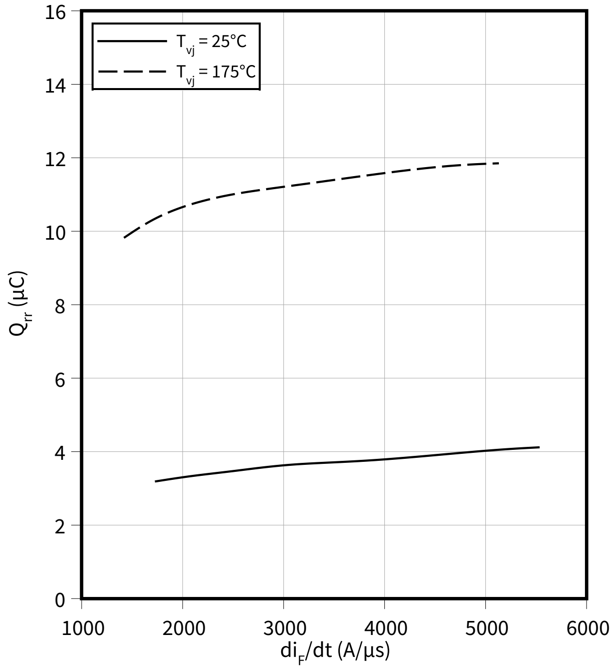
$V_R = 400$ V, $I_F = 150$ A



Typical reverse recovery charge as a function of diode current slope

$Q_{rr} = f(di_F/dt)$

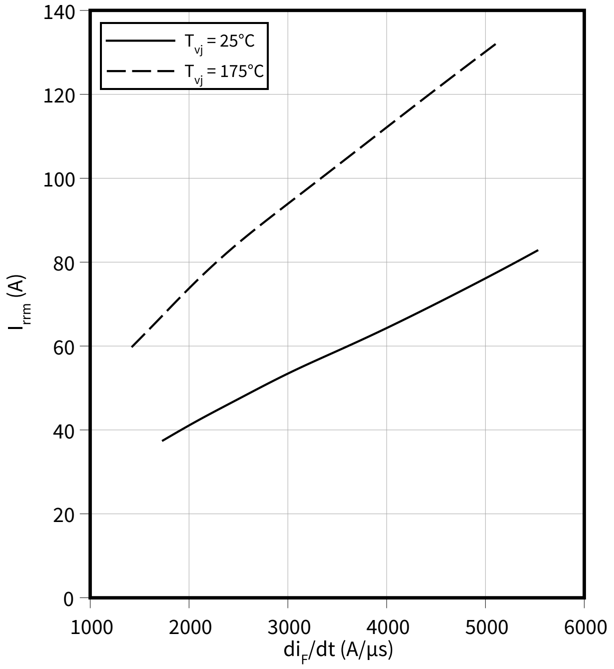
$V_R = 400$ V, $I_F = 150$ A



Typical reverse recovery current as a function of diode current slope

$I_{rrm} = f(di_F/dt)$

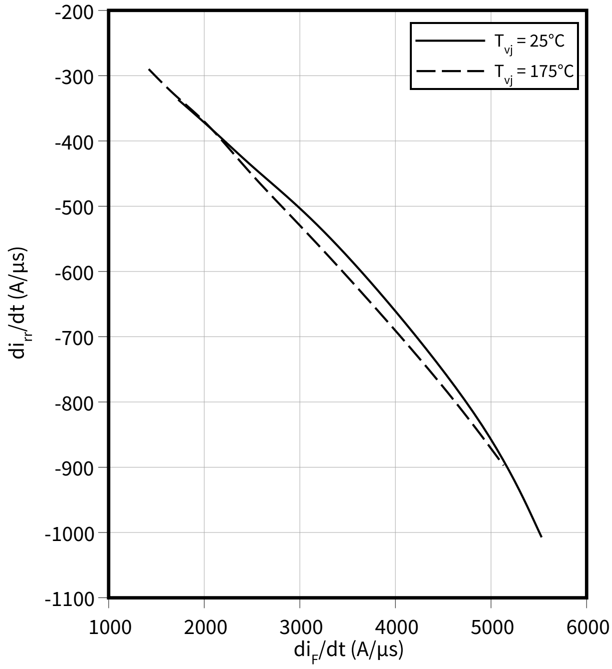
$V_R = 400$ V, $I_F = 150$ A



Typical diode peak rate of fall of reverse recovery current as a function of diode current slope

$di_{rr}/dt = f(di_F/dt)$

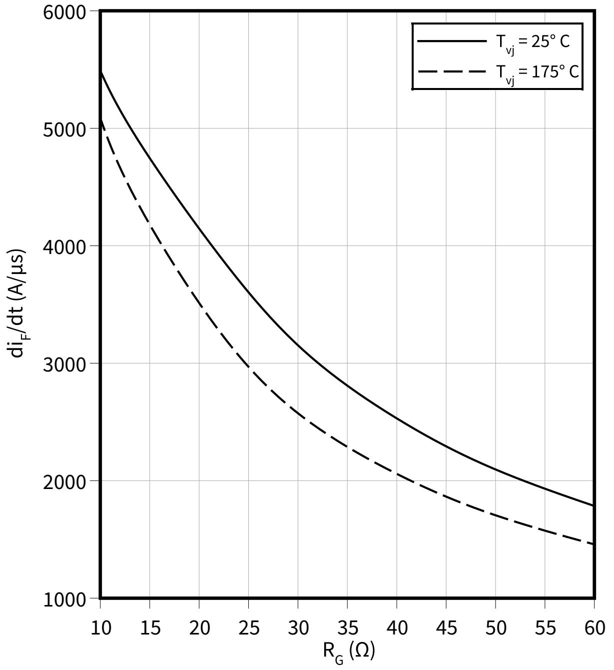
$V_R = 400$ V, $I_F = 150$ A



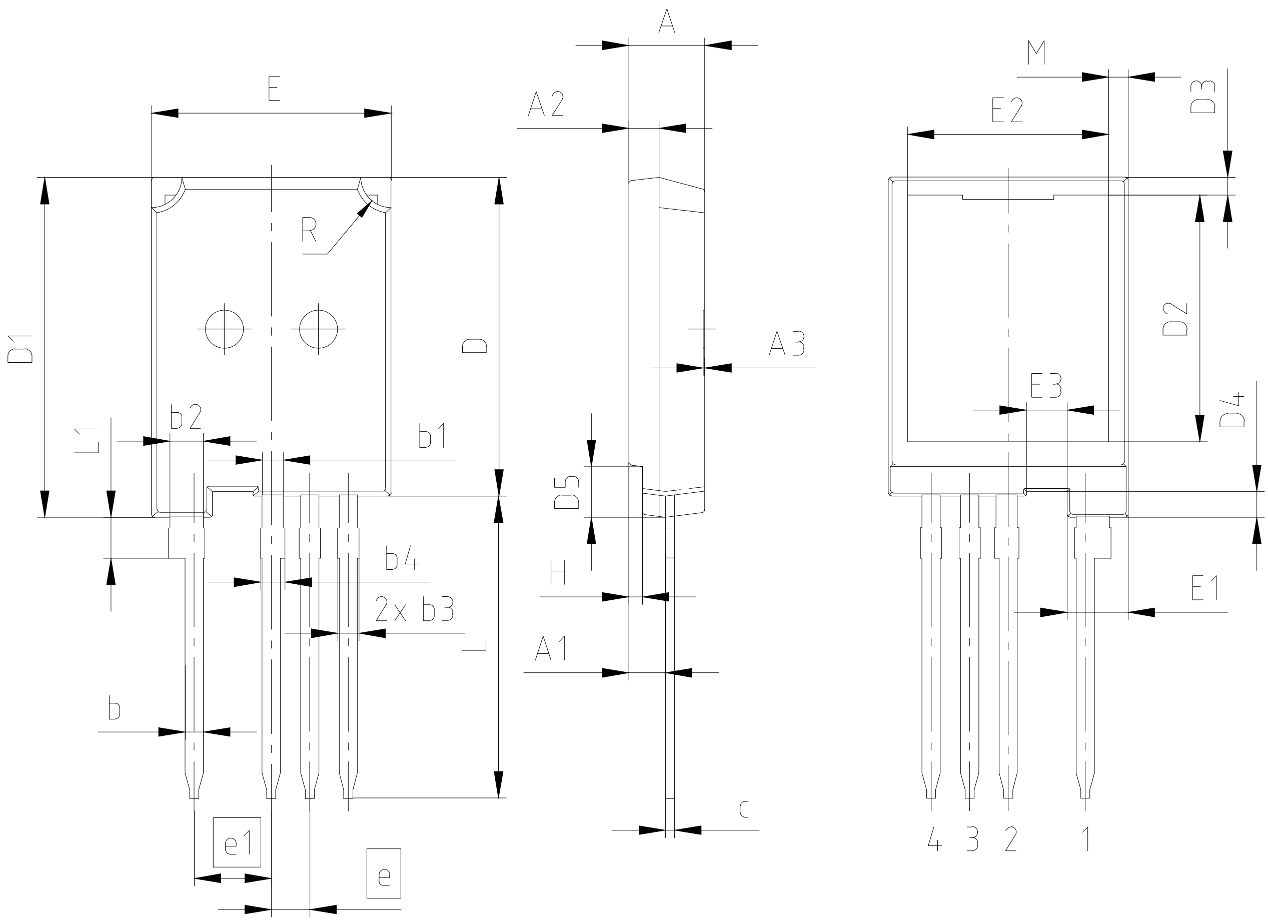
Typical diode current slope as a function of gate resistor

$di_F/dt = f(R_G)$

$V_R = 400$ V, $I_F = 150$ A



5 Package outlines



NOTES:
PACKAGE SURFACE ROUTE BETWEEN PIN 1 & PIN 2 WILL BE 5.1 mm MIN.
ALL b... AND c DIMENSIONS INCLUDING PLATING EXPECT AREA OF CUTTING

PACKAGE - GROUP NUMBER: **PG-TO247-4-U10**

DIMENSIONS	MILLIMETERS		DIMENSIONS	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	4.90	5.10	**E**	15.70	15.90
A1	2.31	2.51	**E1**	3.90	4.10
A2	1.90	2.10	**E2**	13.10	13.50
b	1.16	1.29	**E3**	2.58	2.78
b1	1.36	1.49	**e**	2.54	
b2	2.16	2.29	**e1**	5.08	
b3	1.16	1.45	**H**	0.80	1.00
b4	1.16	1.65	**N**	4	
c	0.59	0.66	**L**	19.80	20.10
D	20.90	21.10	**L1**	2.55	2.85
D1	22.30	22.50	**M**	0.97	1.57
D2	15.95	16.55	**R**	1.90	2.10
D3	1.00	1.35			
D4	1.60	1.80			
D5	3.24	3.44			

Figure 1

6 Testing conditions

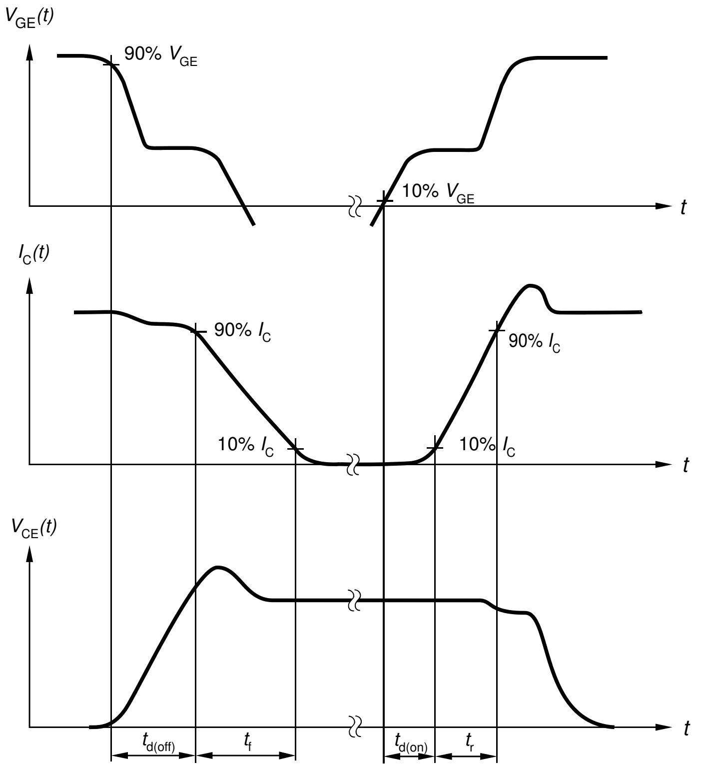


Figure A. **Definition of switching times**

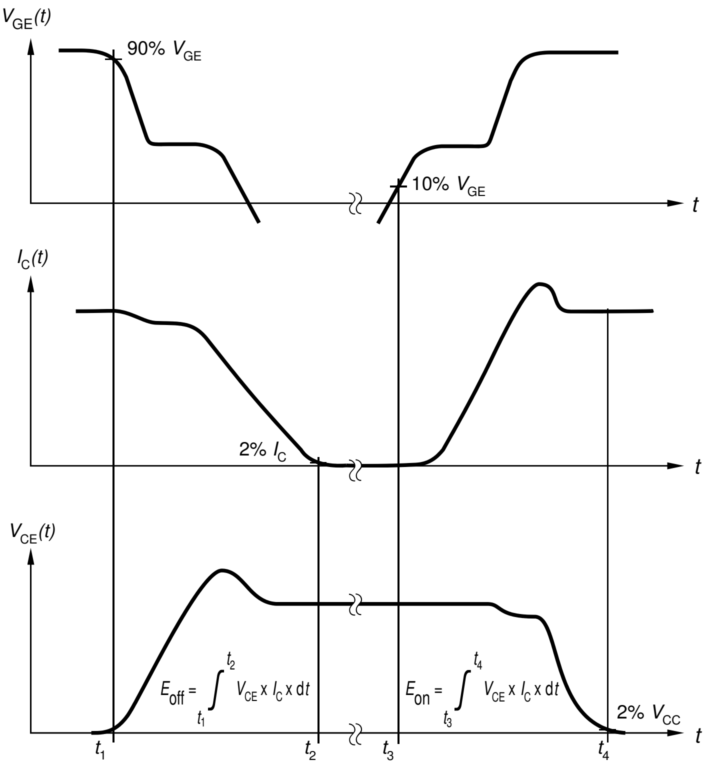


Figure B. **Definition of switching losses**

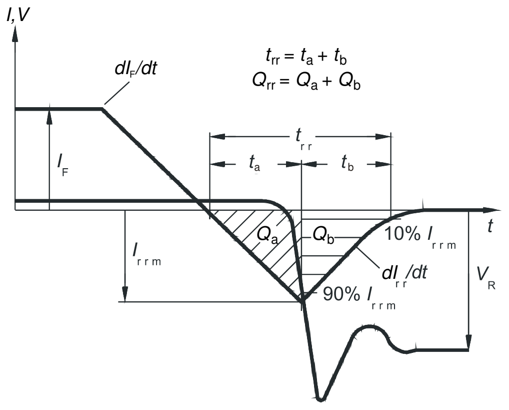


Figure C. **Definition of diode switching characteristics**

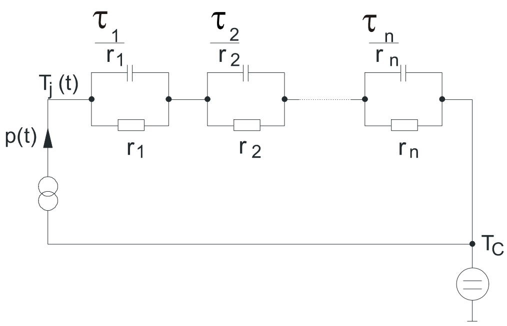


Figure D. **Thermal equivalent circuit**

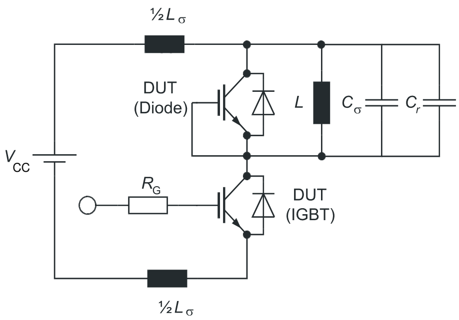


Figure E. **Dynamic test circuit**
Parasitic inductance L_{σ},
parasitic capacitor C_{σ},
relief capacitor C_{r},
(only for ZVT switching)

Figure 2

Revision history

Document revision	Date of release	Description of changes
0.10	2025-06-17	Preliminary datasheet
1.00	2025-07-31	Final datasheet

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

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